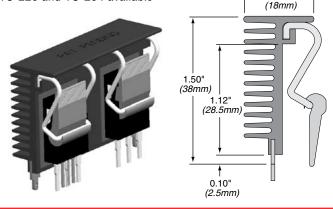
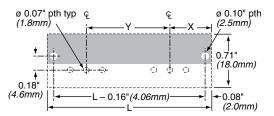
C Series TO-247 Package Heatsinks

TO-220 and TO-264 available



Heatsink Part Number	Surface Area (in ² /mm ²)	Weight (oz/g)	Length "L" (mm)
C247-025	11 / 7,312	0.5 / 15	25
C247-050	23 / 14,858	1.1 / 31	50
C247-075	34 / 21,655	1.6 / 45	75

LAND PATTERN



STANDARD PART NUMBERS FOR C SERIES

Part Number	Description	Packaging
C247-025-1VE	Heat sink, no finish (degreased)	Bulk
C247-025-1AE	Heat sink, black anodized	Bulk
C247-050-2VE	Heat sink, no finish (degreased)	Bulk
C247-050-2AE	Heat sink, black anodized	Bulk
C247-075-3VE	Heat sink, no finish (degreased)	Bulk
C247-075-3AE	Heat sink, black anodized	Bulk

ORDERING INFORMATION

C 2 4 7 - 2 5 - 1 A E Series Clip size Clip si Ohmite introduces the C series (Pat. Pending). This series offers high performance, low cost and a compact heat sink with an integrated camming clip system for TO-247 packages (TO-220 and TO-264 available). This powerful heat sink provides tool and fixture free assembly operation, largest surface areas and smallest space occupation. It is the ideal type of heat sink for high power density and small size (1U or 2U) electronic packaging with forced convention cooling.

F E A T U R E S

0.71"

Minimum assembly cost and labor Spring Clips make the mounting holes, fasteners, tools and fixtures obsolete in assembly operations & reduce costs.

- Maximum Thermal Transfer Maximum surface area per unit volume, efficient cooling fins & consistent mounting force reduces thermal resistance.
- Maximum Repeatability Constant spring force over repeated assembly/disassembly.
- Maximum Reliability Resilient spring action locks electronic component in place. Fewer parts in assembly and no fasteners and washers required. Prevent short circuit by eliminating metal particles generated from hardware or thread tapping.
- Design Flexibility Maximum flexibility for dynamic device locations and power upgrading. "Configure-to-Fit" gives designers total freedom to configure heat sink needed to fit into a multitude design environments.

HEAT DISSIPATION

L = 1.97" (50mm) Air Velocity (ft./min.) 200 400 800 1000 600 140 6 ŝ Mounting 120 5 Rise above Ambient rmal Resistance from Moun Case to Ambient (°C/watts) 100 4 80 з 60 2 Case Temp. 40 Thermal 20 0 0 5 10 0 15 Heat Dissipated, total for two devices (watts)

<u>S P E C I F I C A T I O N S</u>

- Heat Sink: Aluminum Alloy 6063-T5 or Equivalent with either degreased or black anodized finish.
- Spring Clip: Music Wire, Per ASTM A228 with bright nickel plating
- Solder Foot: Cold-rolled Steel, Per ASTM A-366 with pure tin over copper strike. RoHS compliant.
- Interface Thermal Resistance: for improvement, use thermal joint compound, 0.005 Grafoil (TGon 800 by Laird), or phase change material (Hi-Flow by Bergquist)
- **Insulator** (Optional): Sil-Pad 900-S, K6 800-S and K10 by Bergquist